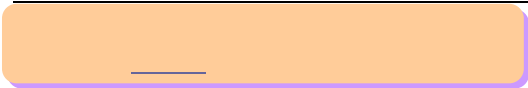


有铅

Sn50/Pb50 SnPbBi

- 1 0.4mm
- 2 12
- 3
- 4
- 5
- 6 --- PCB
- 7 ICT
- 8 Paste in hole

| | | | |
|-------|------|----------------------------------|------------------------------|
| | | | |
| | | ROL1 | J-STD-004 |
| | | 0.2wt% | |
| (SIR) | | 1 10 ¹³ | 25mil |
| | | 1 10 ¹² | 40 90%RH 96Hrs |
| | | 1 10 ⁵ | |
| | | | IPC-TM-650 |
| | | | IPC-TM-650 |
| | | | In house |
| | | | |
| | | 85~91wt% ± 0.5 | |
| | | 9~15wt% ± 0.5 | |
| | | 200 Pa.s ±10% Malcolm (10rpm,2) | T3,90% metal for printing |
| | | 80 Pa.s ±10% Malcolm (10rpm,2) | T4,87% metal for syringe |
| | | 0.55 ± 0.05 | In house |
| | | 90% | Copper plate(Sn63,90% metal) |
| | | | J-STD-005 |
| | | | In house |
| Vs | 48gF | 0 | IPC-TM-650 ± 5% |
| | 56gF | 2 | |
| | 68gF | 4 | |
| | 44gF | 8 | |
| | | 12 | In house |
| | | | 0~10 |
| | | | |



1

T3 mesh -325/+500 25~45 m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

(适当的搅拌时间因搅拌方式、装置及环境温度等因素而有所不同，应在事前多做试验来确定)。

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

| | |
|--|--|
| | 60 ~ 90HS |
| | 45 ⁰ ~ 60 ⁰ |
| | 2 ~ 4 10 ⁵ pa |
| | 20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec |
| | 25 ± 3 40 ~ 70% |



*

*

*

PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

-
-

0

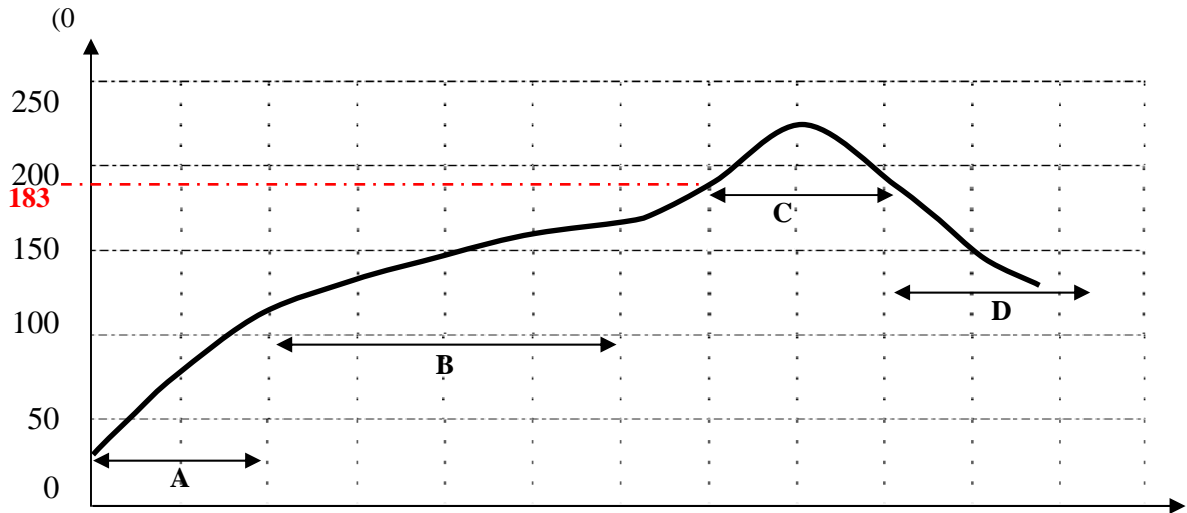
6



MSDS

有铅

Sn50/Pb50 SnPbBi



A. _____ 25~33%

* 1.0~3.0 /
*

B. _____ 33~50%

* _____ PCB 1.5 /
* 150~200 60~90

C. _____

* 230~245 183 70~90 Important 200 50~65
*
*

D. _____

* 4 75
*
*

